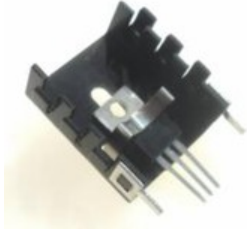
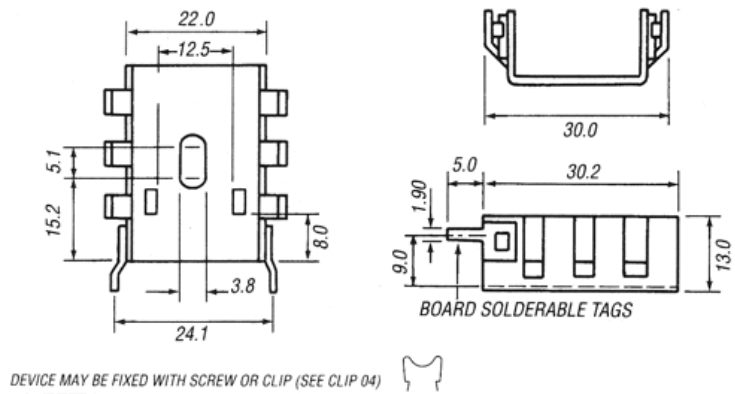


Heat sink Details for LS220



This heatsink is suitable for use with device(s): TO220, TO218

Thermal Performance: 17.00 °C/W



All dimensions shown are subject to commercial tolerances. Details of individual tolerances and fully dimensioned drawings available on request.

Where a device is shown it is for illustrative purposes only. The heat sink is supplied without device. Most board mount and bga heatsinks are supplied black anodised to assist thermal performance.

Thermal Resistance is calculated based on a distributed heat load on anodised heatsink with vertically mounted fins based on a 60°C temperature rise. Under general operating conditions the thermal mounting arrangement of devices is not known and therefore the figures should be used only as a guide to selection.

We recommend that the effectiveness of any heat sink is tested in the specific operating environment in which it will be subjected. All information is for reference purposes only.